# **BGA Heat Sink - High Performance** maxiFLOW/superGRIP



#### ATS Part#:

Description:

#### ATS-X50310P-C1-R0

31.00 x 31.00 x 17.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP

Heat Sink Type: Heat Sink Attachment: Equivalent Part Number: N/A

maxiFLOW superGRIP

\*Image above is for illustration purpose only.

### Features & Benefits

- Designed for 31 x 31 mm components •
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs •
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a • PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB .

## **Thermal Performance**

		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.3 °C/W	2.7 °C/W	2.3 °C/W	2.1 °C/W	1.9 °C/W	1.8 °C/W	1.7 °C/W
	Ducted Flow	2.7	N/A	N/A	N/A	N/A	N/A	N/A

## **Product Detail**

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	31.00 mm	31.00 mm	17.50 mm	54.9 mm	T766	BLUE-ANODIZED
The above is for illustration purpose only.	<ul> <li>Dimension</li> <li>Thermal papplication</li> <li>ATS resense</li> <li>performant</li> <li>ATS certification</li> </ul>	performance data are n. rves the right to upda nce. ries that this heat sin	omponent size. height from the bottor e provided for referen ate or change its pro- k assembly is RoHS istom options availat	nce only. Actual perfo ducts without notice -6 and REACH com	ormance to improv	may vary by

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